

ABSTRACT

A manufacturing method of a substrate for a semiconductor element, the manufacturing method including the steps of: providing a first photosensitive resin layer at a first surface of a metal plate; providing a second photosensitive resin layer at a second surface of the metal plate different from the first surface; forming a first etching mask for forming a connection post on the first surface of the metal plate; forming a second etching mask for forming a wiring post on the second surface of the metal plate; forming the connection post by performing an etching on the first surface of the metal plate from a first surface side to a midway of the metal plate; applying a premold resin in liquid form to the first surface of the metal plate which underwent the etching on the first surface; forming a premold resin layer by solidifying the premold resin in liquid form being applied; and forming a wiring pattern by performing an etching on the second surface of the metal plate from a second surface side.



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